







18th International Forum on MPSoC for Software-defined Hardware July 29 - August 3, 2018, The Cliff Lodge, Snowbird, UT, 84092, USA

General Chair:

Program Co-Chairs:

Anca Molnos, CEA-LETI, France

Jishen Zhao, UC San Diego, USA

Multicore and Multiprocessor SoC (MPSoC) started a new FOCUS computing era but brought a twofold challenge: building HW easy to use by SW designers and building SW that fully exploits HW capabilities. The main domains addressed at MPSoC are related to adapting HW and SW for better cost, performances and energy efficiency of next generation computing systems. Emerging SW and HW design technologies and architectures combined with advanced semiconductor manufacturing technologies are explored to build energy efficient multicore architectures serving advanced computing (image, vision and cloud) and distributed networked systems.

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MPSoC is an interdisciplinary forum bringing together key R&D actors from the different fields required to design Multicore and multiprocessor HW and SW

systems. The program brings together experts in major HW and SW architectures (Processor, Memory, I/O, Interconnect, RTOS, GFX, Virtualization, application-(domain) specific acceleration & system architectures), design technologies (parallel programming, rapid prototyping, system design models and tools) and emerging semiconductor technologies (heterogeneous integration, 3D, photonics) to build next-generation thinking that will bridge the gap between HW and SW. Around 60 world class R&D speakers will discuss fundamental and strategic issues to master Software-defined Hardware for energy-efficient and highperformance computing.

The program includes keynotes on major HW and SW trends and technical sessions to present strategic directions and state-of-the-art research. The 5-day program will also include in-depth technology challenge presentations and short keynotes followed by insightful panels. All the talks will be given by CTO-level speakers from Industry and world-class professors from Academia.

WHY ATTEND

Thanks to its full week format and the high quality of both attendees and speakers, MPSoC is a unique opportunity for executives and senior managers to

explore new ideas and refine strategic thinking. MPSoC is the single best event in the world that brings together so many leading thinkers on the future of HW and SW design. It enables great informal networking and interactions with experienced, distinguished researchers and top academic and industrial experts. It builds bridges between different technical areas and corporations, institutes and countries. Finally, it is a unique environment for anyone who wants to share knowledge with researchers and key managers from industry.

days and dinner for five days including the social dinner.



For registration before May 31, the fee amounts to 1400 USD for regular attendees, 1190 USD for IEEE and EDAA members, and 850 USD for speakers. Each speaker is allowed to invite Junior attendee (student) with a fee of 790 USD. It will cover the documentation, the lunch for five

European Liaison Frédéric Petrot, TIMA-INP Grenoble, France Nicolas Ventroux, CEA-LIST, France North American Liaison: Gabriela Nicolescu, Poly. Montreal, Canada Asian Liaison: Shinya Takamaeda-Yamazaki, Hokkaido University, Japan Sungjoo Yoo, Seoul National University, Korea **Industry Liaison:** Andreas Herkersdof, TUM, Germany Yoshifumi Sakamoto, IBM, Japan Yuan Xie, UC Santa Barbara, USA Local Organization Chair: Tom Becnel, University of Utah, USA Finance Chair: Frédéric Rousseau, TIMA-UGA, France Ken Stevens, University of Utah, USA **Publicity Chair:** Fabien Clermidy, CEA-LETI, France Koji Inoué, Kyuchu University, Japan **Proceedings Chair:** Tom Becnel, University of Utah, USA Web Chair Edouard Giacomin, University of Utah, USA **Technical Program Committee:** Marcello Coppola, STMicroelectronics, France Raphaël David, CEA-List, France Giovanni De Micheli, EPFL, Switzerland Rolf Ernst, TU Braunschweig, Germany John Goodacre, ARM, UK Kees Goossens, TUE, The Netherlands Masaharu Imai, Osaka University, Japan Koji Inoue, Kvushu University, Japan Tsuyoshi Isshiki, Tokyo Institute of Tech., Japan Ahmed Jerraya, CEA-Leti, France Rainer Leupers, RWTH Aachen University, Germany Youn-long Lin, National Tsing Hua University, Taiwan Takashi Miyamori, Toshiba Corp., Japan Gabriela Nicolescu, Polv. Montreal, Canada Pierre Paulin, Synopsys, Canada Frederic Pétrot, TIMA-INPG, France Yoshinori Takeuchi, Kindai University, Japan Hiroyuki Tomiyama, Ritsumeikan University, Japan Kees Vissers, Xilinx, USA Norbert Wehn, University of Kaiserslautern, Germany Marilyn Wolf, Georgia Institute of Tech., USA Yuan Xie, UC Santa Barbara, USA Hiroto Yasuura, Kyushu University, USA Sungjoo Yoo, Seoul National University, Korea

Pierre-Emmanuel Gaillardon, University of Utah, USA

Yoshinori Takeuchi, Kindai University, Japan

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KEYNOTES (6)

- Rob Aitken, ARM, UK
- Vance Checketts, *Dell EMC, USA*
- Paul Joyce, *Dell EMC, USA*
- Ike Nassi, *TidalScale, US*
- Shuichi Yamane, Socionext Inc., Japan
- Farhang Yazdani, Broadpak, US

IN-DEPTH PRESENTATIONS (18)

- Gerhard Fettweis, TU Dresden, Germany
- Masaki Gondo, eSOL Co., Ltd., Japan
- Yoshihiko Hirota, Konica Minolta, Japan
- Masatoshi Ishii, IBM Research Tokyo, Japan
- K. Charles Janac, Arteris Inc., USA
- Shahar Kvatinsky, *Technion, Israël*
- Peter van der Made, BrainChip Inc., USA
- Takashi Miyamori, *Toshiba Corporation, Japan*
- Anush Mohandass, NetSpeed Systems, USA
- Masahiro Murakami, Konica Minolta, Japan
- Yuichi Nakamura, NEC Corp., Japan
- Francois Neumann, Safran Electronics & Defense, France
- Greg Nielson, Nielson Scientific, USA
- Pei-Lin Pai, Winbond, Taiwan
- Pierre Paulin, Synopsys, Canada
- Yankin Tanurhan, Synopsys, USA
- Kees Vissers, Xilinx, USA
- Yuan Xie, UCSB, USA

MINI-KEYNOTES (38)

- Fumio Arakawa, *The University of Tokyo, Japan*
- Gerd Ascheid, *RWTH Aachen University, Germany*
- Kees van Berkel, Ericsson, Eindhoven University of Technology, The Netherlands
- Rolf Ernst, Technische Universitat Braunschweig, Germany
- Ran Ginosar, Technion-Israel Institute of Technology, Israël
- John Goodacre, ARM, UK
- Arnaud Grasset, *Thales Research & Tech.*, *France*

MINI-KEYNOTES (38)

- Victor Grimblatt, Synopsys Chile R&D Center, Latin America
- Yuko Hara-Azumi, Tokyo Institute of Technology, Japan
- Andreas Herkersdorf, TU Munich, Germany
- Tohru Ishihara, Kyoto University, Japan
- Tsuyoshi Isshiki, Tokyo Institute of Technology, Japan
- Masaaki Kondo, The University of Tokyo, Japan
- Youn-Long Lin, National Tsing Hua University, Taiwan
- Hiroki Matsutani, Keio University, Japan
- Pankaj Mehra, Western Digital Corporation, USA
- Anca Molnos, CEA-Leti, France
- Eric Monchalin, ATOS, France
- Gabriela Nicolescu, Ecole Polytechnique de Montréal, Canada
- Danilo Pau, STMicroelectronics, Italy
- Frédéric Pétrot, TIMA Lab, Grenoble University, France
- Frédéric Rousseau, TIMA Lab, Grenoble University, France
- Yoshifumi Sakamoto, IBM Japan, Japan
- Tsuyoshi Sato, Pioneer, Japan
- Weihua Sheng, Silexica, Germany
- Akihiko Shinya, NTT Nanophotonics Center, Japan
- Shinya Takamaeda, Hokkaido University, Japan
- Yoshinori Takeuchi, Kindai University, Japan
- Ittetsu Taniguchi, Graduate School of Information Science and Technology Osaka University, Japan
 - Hiroyuki Tomiyama, Ritsumeikan University, Japan
- Nicolas Ventroux, CEA-List, France
- Norbert Wehn, University of Kaiserslautern, Germany
- Marilyn Wolf, Georgia Tech, USA
- Jiang Xu, Hong Kong University of Science and Technology, Hong Kong
- Song Yao, DeePhi Tech, China
- Sungjoo Yoo, Seoul National University, Korea
- Wei Zhang, Hong Kong University of Science and Technology, Hong Kong
- Jishen Zhao, UCSD, USA

Total speakers: 62

MPSoC'18 FORUM REGISTRATION FORM

For registration **before May 31**, the fees are 1400 USD for regular attendees, 1190 USD for IEEE and EDAA members and 850 USD for Speakers. Each speaker is allowed to invite a Junior attendee (student or engineer) with an additional fee of 790 USD. The fee will cover the documentation, the lunch for five days, dinner for four days including the social dinner.

Please mail or fax this form to: MPSOC'18 – MP Associates Inc., 1721 Boulder St. Ste. 107, Louisville, CO 80027 - USA Tel: +1 (303) 530-4562 Fax: +1 (303) 530-4334

	Last Name	Company					
Address			City	/	State	Zip	
Country		Fax	Email				
Advance registratio	on (before May 31, 2018) -	- Circle your choice(s	5)				
Regular attendee 1400 USD	IEEE/EDAA member 1190 USD	Student/Junior 790 USD	Speaker 850 USD	2 Days 850 USD			
TOTAL FEES	USD						
For 2 days only, plea	se circle your choice: Sun/	Mon Mon/Tue	e Tue/We	ed Wed	/Thu	Thu/Fri	
U.S. banks the attend	U.S. dollars with this form dee will be charged a collect lake U.S. checks payable to	ction fee of US \$30.00					
date	dVisa Mastercard					Exp.	
Name (as it appears	on card)	card) Signature					

Refunds:

Requests for refunds received before May 31, 2018 will be subjected to a \$50 processing fee. No refunds will be made for cancellations received after May 31, 2018 and all registration fees will be forfeited. Register early to avoid disappointment.

MPSoC'18 HOTEL BOOKING



MPSoC'18 will be held in Snowbird, UT, USA From July 29 to August 3, 2018

The Cliff Lodge 9320 South Cliff Lodge Dr Snowbird, UT, 84092, USA

Further information is available at: http://www.mpsoc-forum.org/